

ABSTRACT

METHODS AND APPARATUS FOR CHANGING AREA RATIO IN A PLASMA PROCESSING SYSTEM

A plasma processing system having an upper electrode and a lower electrode. The upper electrode and lower electrode form two regions with different gaps. By moving one or both of the upper electrode and the lower electrode, it is possible to vary the ratio area of RF coupling depending on whether plasma is permitted to sustain in the first region or in both the first region and the second region.

FIG. 5